

623-0303-H11 General Specifications

■ Mechanical

- Typical Application: BGA
- Minimum Device Pitch: 0.65 mm
- Force: 30 gf @ 0.60 mm Recommended Travel
- Operating Temperature Range: -55°C to 150°C
- Device Side Contact: 4-point Crown Tip
- PCB Side Contact : Conical Radius Tip

■ Electrical

- Bandwidth @ -1 dB: up to 20 GHz
 - Based on G-S-G Pattern
- Contact Resistance: < 50 mΩ average
- Current Carrying Capability: 3.0 A
 - Measured in free air

■ Plating

- Device Side Plunger: Homogenous alloy
- PCB Side Plunger : Gold plated
- Barrel: Gold plated
- Spring: Gold plated

